

HEAT SINK/TRANSISTOR GREASE

Heat sink draws heat away when applied to a component. In electronics, heat sink compound is generally used to thermally bond a component with a mechanical heat sink. For electrical applications, it is used with thermocouple wells, thermistors, and calorods, or wherever efficient cooling is required.



1977

SILICONE HEAT SINK COMPOUND

Ideal for electrical applications.

- Functional Temperature Range
-67°F to 401°F (-55°C to 205°C)
- Easy Application
- Will Not Harden and Crack

1977-DP 4 oz squeeze tube



1978

SILICONE-FREE HEAT SINK COMPOUND

Ideal for electronic applications where silicone contamination hurts solderability and increase solder defects.

- Functional Temperature Range
-40°F to 392°F (-40°C to 200°C)
- Avoid Solder Defects Due to Silicon Contamination
- Easy Application
- Will Not Separate
- Will Not Harden and Crack

1978-DP 4 oz squeeze tube

1978-1 1 lb jar



1978-DP